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#20/D
11-1701

Staris

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): IWASAKI, et al.
Serial No.: 09/255,856
Filed: February 23, 1999
For: SEMICONDUCTOR DEVICE WITH LAYERED
INTERCONNECT STRUCTURE
Group: 2813
Examiner: S. Smoot

TECHNICAL STAFF
11/13/2001

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

November 6, 2001

Sir:

In response to the Office Action mailed July 6, 2001, please amend the
above-identified application as follows:

IN THE CLAIMS

Please amend the claims presently in the application as follows:

1. (Twice Amended) A semiconductor device with a multilayered
structure comprising a copper film interconnect formed on one primary surface
of a semiconductor substrate, and a neighboring film formed in contact with said